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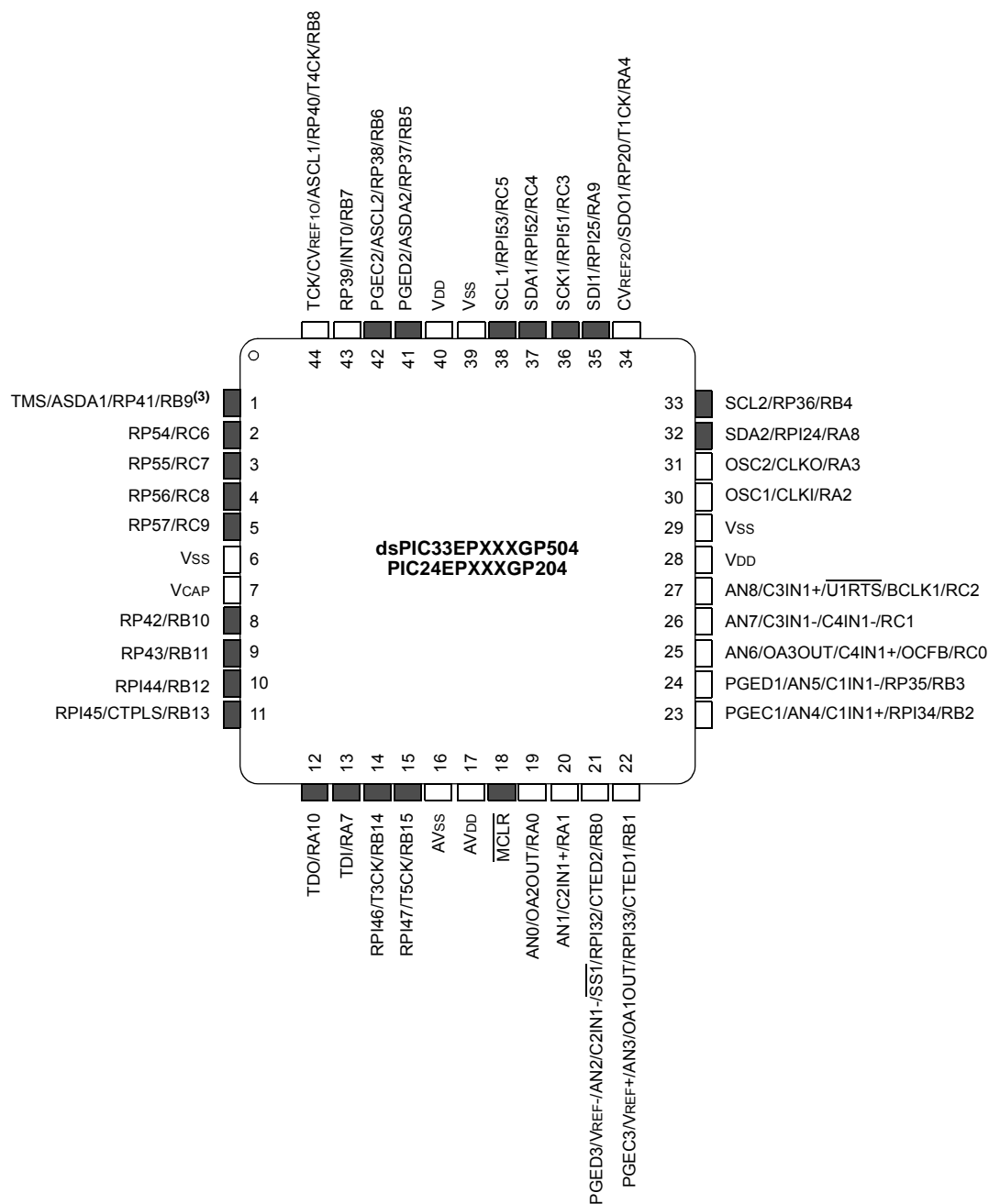
Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256mc204-i-pt

Pin Diagrams (Continued)

44-Pin TQFP^(1,2)

■ = Pins are up to 5V tolerant



- Note** 1: The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- 2: Every I/O port pin (RAX-RGx) can be used as a Change Notification pin (CNAX-CNGx). See **Section 11.0 “I/O Ports”** for more information.
- 3: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-5: PROGRAM MEMORY MAP FOR dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X AND PIC24EP512GP/MC20X DEVICES

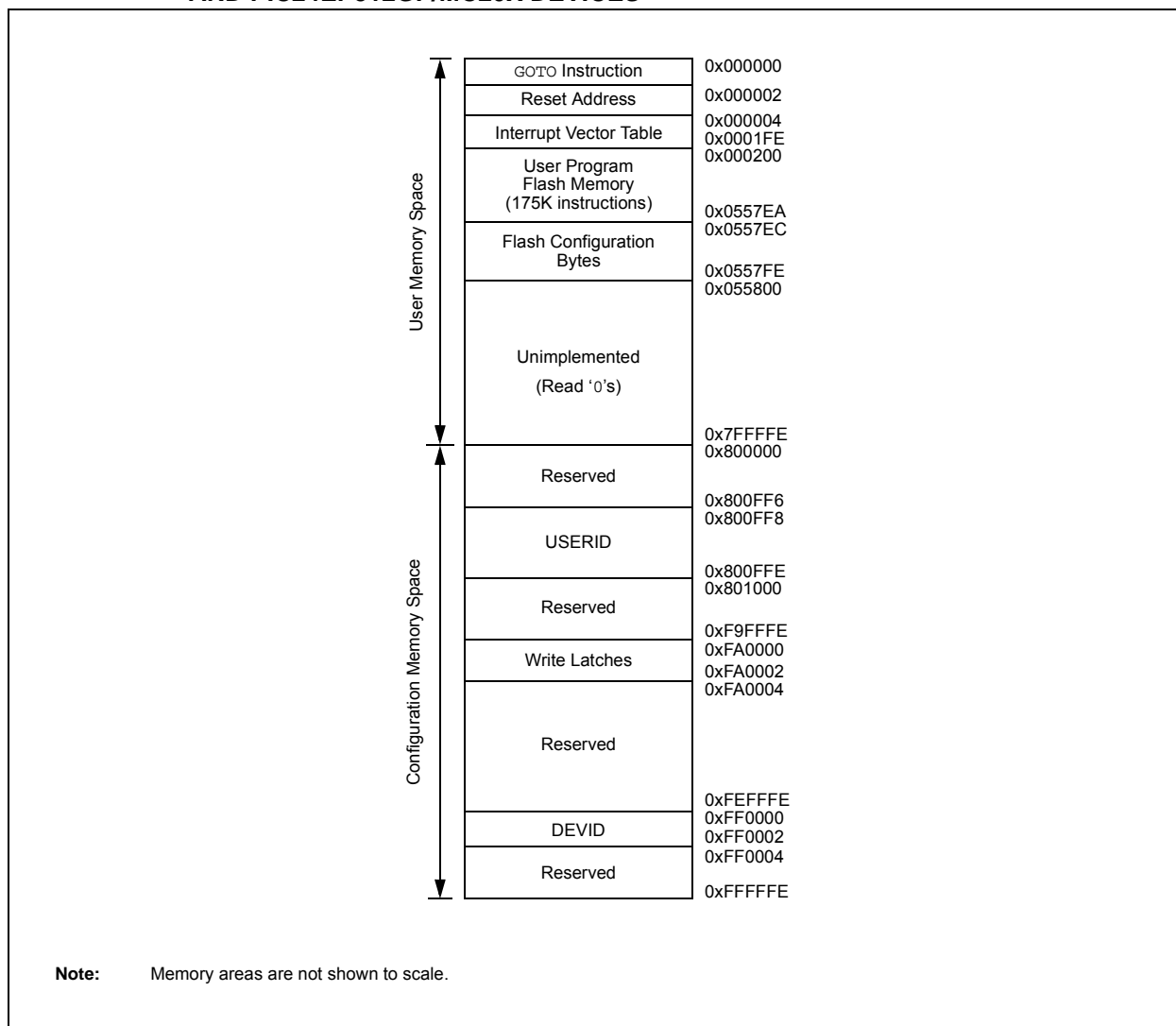


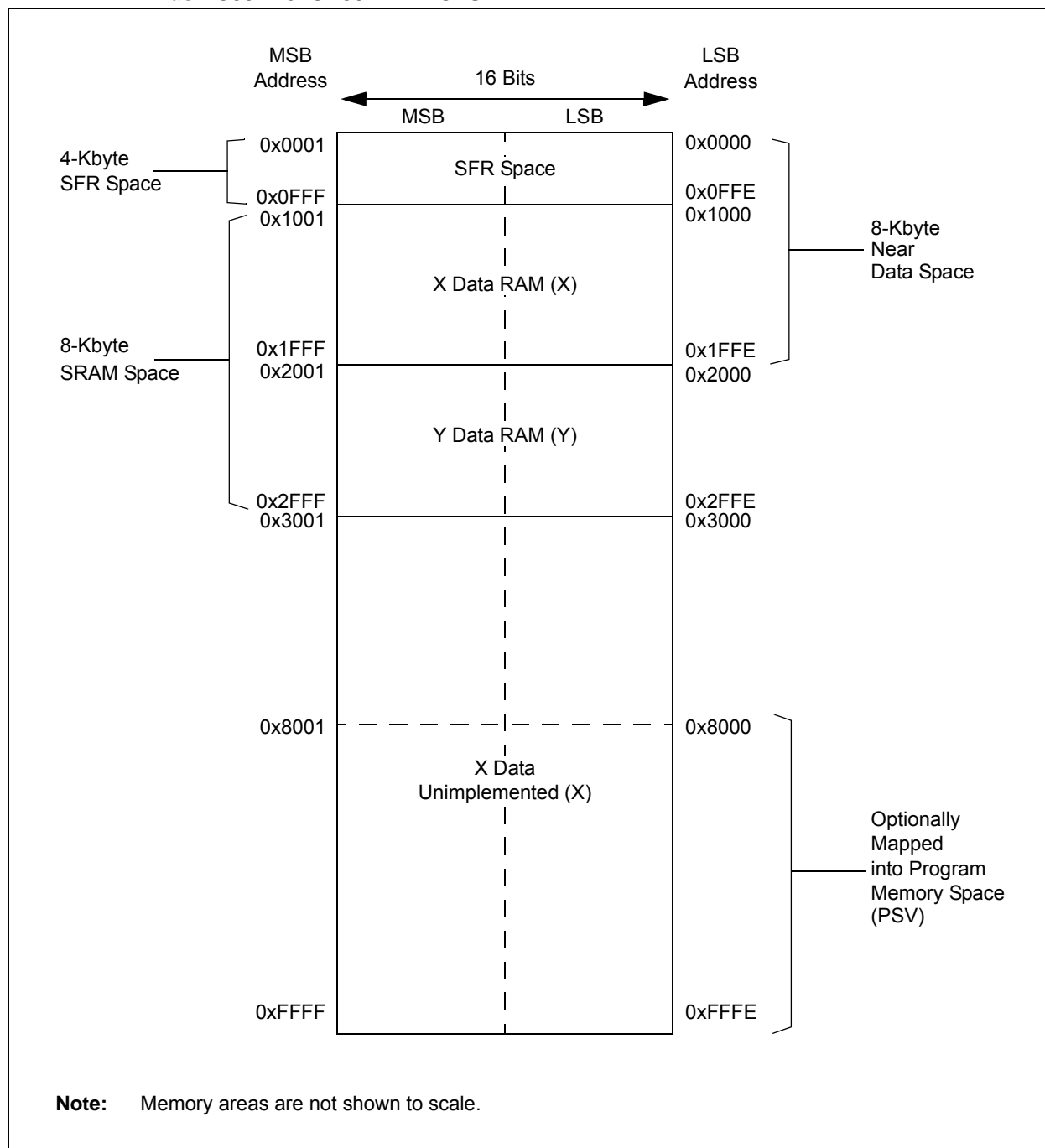
FIGURE 4-8: DATA MEMORY MAP FOR dsPIC33EP64MC20X/50X AND dsPIC33EP64GP50X DEVICES

TABLE 4-33: PERIPHERAL PIN SELECT INPUT REGISTER MAP FOR dsPIC33EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets		
RPINR0	06A0	—	INT1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR1	06A2	—	—	—	—	—	—	—	—	—	INT2R<6:0>								0000	
RPINR3	06A6	—	—	—	—	—	—	—	—	—	T2CKR<6:0>								0000	
RPINR7	06AE	—	IC2R<6:0>								—	IC1R<6:0>								0000
RPINR8	06B0	—	IC4R<6:0>								—	IC3R<6:0>								0000
RPINR11	06B6	—	—	—	—	—	—	—	—	—	OCFAR<6:0>								0000	
RPINR12	06B8	—	FLT2R<6:0>								—	FLT1R<6:0>								0000
RPINR14	06BC	—	QEB1R<6:0>								—	QEA1R<6:0>								0000
RPINR15	06BE	—	HOME1R<6:0>								—	INDX1R<6:0>								0000
RPINR18	06C4	—	—	—	—	—	—	—	—	—	U1RXR<6:0>								0000	
RPINR19	06C6	—	—	—	—	—	—	—	—	—	U2RXR<6:0>								0000	
RPINR22	06CC	—	SCK2INR<6:0>								—	SDI2R<6:0>								0000
RPINR23	06CE	—	—	—	—	—	—	—	—	—	SS2R<6:0>								0000	
RPINR37	06EA	—	SYNCl1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR38	06EC	—	DTCMP1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR39	06EE	—	DTCMP3R<6:0>								—	DTCMP2R<6:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-2: CORCON: CORE CONTROL REGISTER⁽¹⁾

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1	US0	EDT	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3⁽²⁾	SFA	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
 1 = Variable exception processing is enabled
 0 = Fixed exception processing is enabled

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3⁽²⁾
 1 = CPU Interrupt Priority Level is greater than 7
 0 = CPU Interrupt Priority Level is 7 or less

Note 1: For complete register details, see Register 3-2.

2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

REGISTER 8-12: DMARQC: DMA REQUEST COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-4 **Unimplemented:** Read as '0'bit 3 **RQCOL3:** DMA Channel 3 Transfer Request Collision Flag bit

1 = User force and interrupt-based request collision is detected

0 = No request collision is detected

bit 2 **RQCOL2:** DMA Channel 2 Transfer Request Collision Flag bit

1 = User force and interrupt-based request collision is detected

0 = No request collision is detected

bit 1 **RQCOL1:** DMA Channel 1 Transfer Request Collision Flag bit

1 = User force and interrupt-based request collision is detected

0 = No request collision is detected

bit 0 **RQCOL0:** DMA Channel 0 Transfer Request Collision Flag bit

1 = User force and interrupt-based request collision is detected

0 = No request collision is detected

NOTES:

10.2.1 SLEEP MODE

The following occurs in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals can continue to operate. This includes items such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device wakes up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

For optimal power savings, the internal regulator and the Flash regulator can be configured to go into Standby when Sleep mode is entered by clearing the VREGS (RCON<8>) and VREGSF (RCON<11>) bits (default configuration).

If the application requires a faster wake-up time, and can accept higher current requirements, the VREGS (RCON<8>) and VREGSF (RCON<11>) bits can be set to keep the internal regulator and the Flash regulator active during Sleep mode.

10.2.2 IDLE MODE

The following occurs in Idle mode:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 “Peripheral Module Disable”**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device wakes from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the *PWRSV* instruction or the first instruction in the Interrupt Service Routine (ISR).

All peripherals also have the option to discontinue operation when Idle mode is entered to allow for increased power savings. This option is selectable in the control register of each peripheral; for example, the *TSIDL* bit in the Timer1 Control register (T1CON<13>).

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a *PWRSV* instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

REGISTER 11-26: RPOR8: PERIPHERAL PIN SELECT OUTPUT REGISTER 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP118R<5:0>					
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP118R<5:0>:** Peripheral Output Function is Assigned to RP118 Output Pin bits
(see Table 11-3 for peripheral function numbers)

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 11-27: RPOR9: PERIPHERAL PIN SELECT OUTPUT REGISTER 9

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP120R<5:0>					
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **RP120R<5:0>:** Peripheral Output Function is Assigned to RP120 Output Pin bits
(see Table 11-3 for peripheral function numbers)

15.1 Output Compare Resources

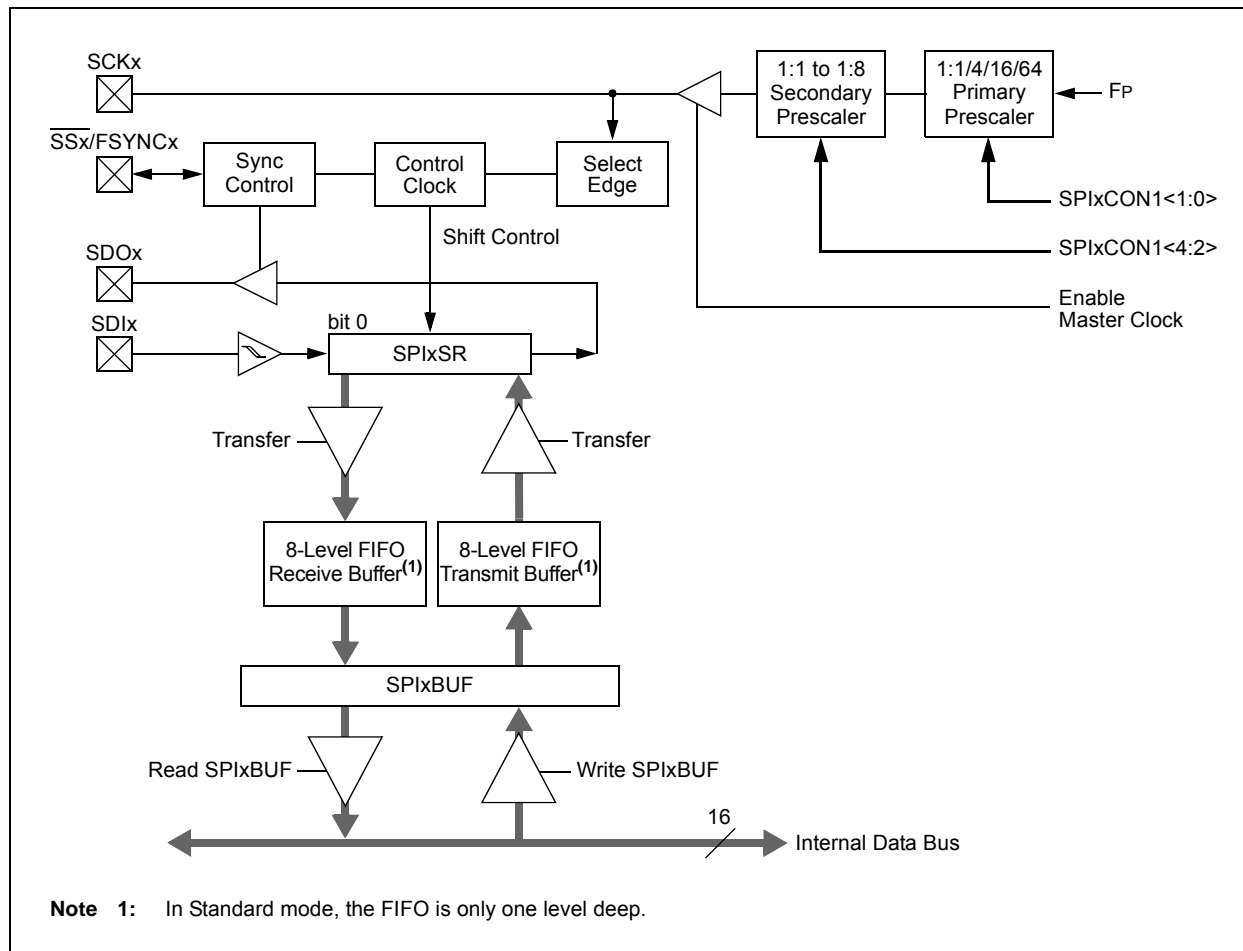
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

15.1.1 KEY RESOURCES

- “**Output Compare**” (DS70358) in the “*dsPIC33/PIC24 Family Reference Manual*”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related “*dsPIC33/PIC24 Family Reference Manual*” Sections
- Development Tools

FIGURE 18-1: SPIx MODULE BLOCK DIAGRAM



19.2 I²C Control Registers

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN ⁽¹⁾	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

- bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I²C™ pins are controlled by port functions
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters an Idle mode
0 = Continues module operation in Idle mode
- bit 12 **SCLREL:** SCLx Release Control bit (when operating as I²C slave)
1 = Releases SCLx clock
0 = Holds SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software can write '0' to initiate stretch and write '1' to release clock). Hardware is clear at the beginning of every slave data byte transmission. Hardware is clear at the end of every slave address byte reception. Hardware is clear at the end of every slave data byte reception.
If STREN = 0:
Bit is R/S (i.e., software can only write '1' to release clock). Hardware is clear at the beginning of every slave data byte transmission. Hardware is clear at the end of every slave address byte reception.
- bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit⁽¹⁾
1 = IPMI mode is enabled; all addresses are Acknowledged
0 = IPMI mode disabled
- bit 10 **A10M:** 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address
- bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control is disabled
0 = Slew rate control is enabled
- bit 8 **SMEN:** SMBus Input Levels bit
1 = Enables I/O pin thresholds compliant with SMBus specification
0 = Disables SMBus input thresholds
- bit 7 **GCEN:** General Call Enable bit (when operating as I²C slave)
1 = Enables interrupt when a general call address is received in I2CxRSR (module is enabled for reception)
0 = General call address disabled

Note 1: When performing master operations, ensure that the IPMIEN bit is set to '0'.

20.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**UART**” (DS70582) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices contains two UART modules.

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device family. The UART is a full-duplex, asynchronous system that can communicate with peripheral devices, such as personal computers, LIN/J2602, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the UxCTS and UxRTS pins, and also includes an IrDA® encoder and decoder.

Note: Hardware flow control using $\overline{\text{UxRTS}}$ and $\overline{\text{UxCTS}}$ is not available on all pin count devices. See the “**Pin Diagrams**” section for availability.

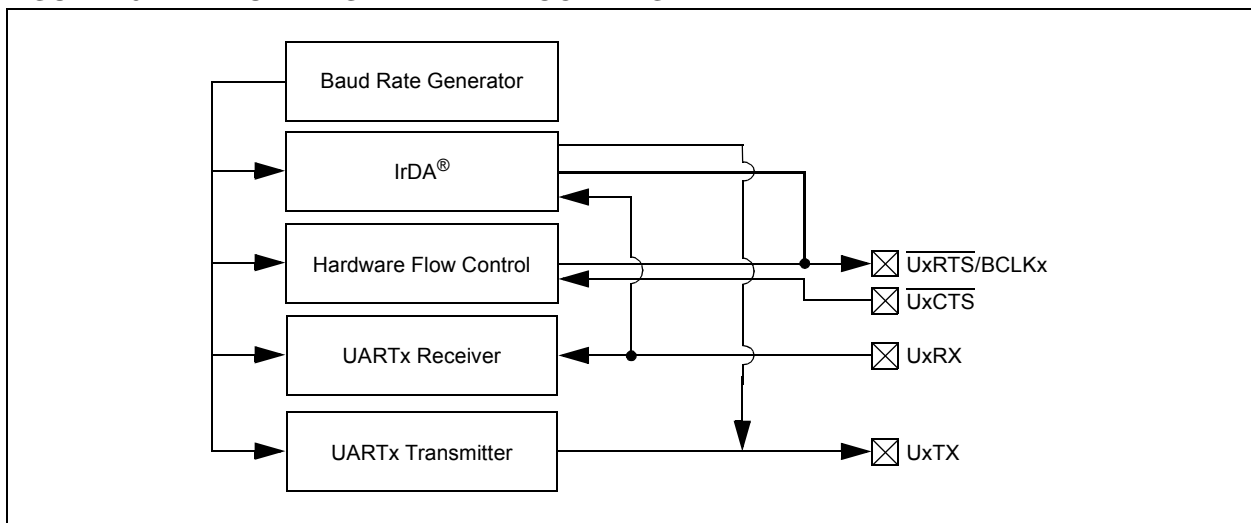
The primary features of the UARTx module are:

- Full-Duplex, 8 or 9-Bit Data Transmission through the UxTX and UxRX Pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop bits
- Hardware Flow Control Option with $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ Pins
- Fully Integrated Baud Rate Generator with 16-Bit Prescaler
- Baud Rates Ranging from 4.375 Mbps to 67 bps at 16x mode at 70 MIPS
- Baud Rates Ranging from 17.5 Mbps to 267 bps at 4x mode at 70 MIPS
- 4-Deep First-In First-Out (FIFO) Transmit Data Buffer
- 4-Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- Transmit and Receive Interrupts
- A Separate Interrupt for all UARTx Error Conditions
- Loopback mode for Diagnostic Support
- Support for Sync and Break Characters
- Support for Automatic Baud Rate Detection
- IrDA® Encoder and Decoder Logic
- 16x Baud Clock Output for IrDA Support

A simplified block diagram of the UARTx module is shown in Figure 20-1. The UARTx module consists of these key hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 20-1: UARTx SIMPLIFIED BLOCK DIAGRAM



REGISTER 21-11: CxFEN1: ECANx ACCEPTANCE FILTER ENABLE REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **FLTEN<15:0>**: Enable Filter n to Accept Messages bits
1 = Enables Filter n
0 = Disables Filter n

REGISTER 21-12: CxBUFNT1: ECANx FILTER 0-3 BUFFER POINTER REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F3BP<3:0>				F2BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F1BP<3:0>				F0BP<3:0>			
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

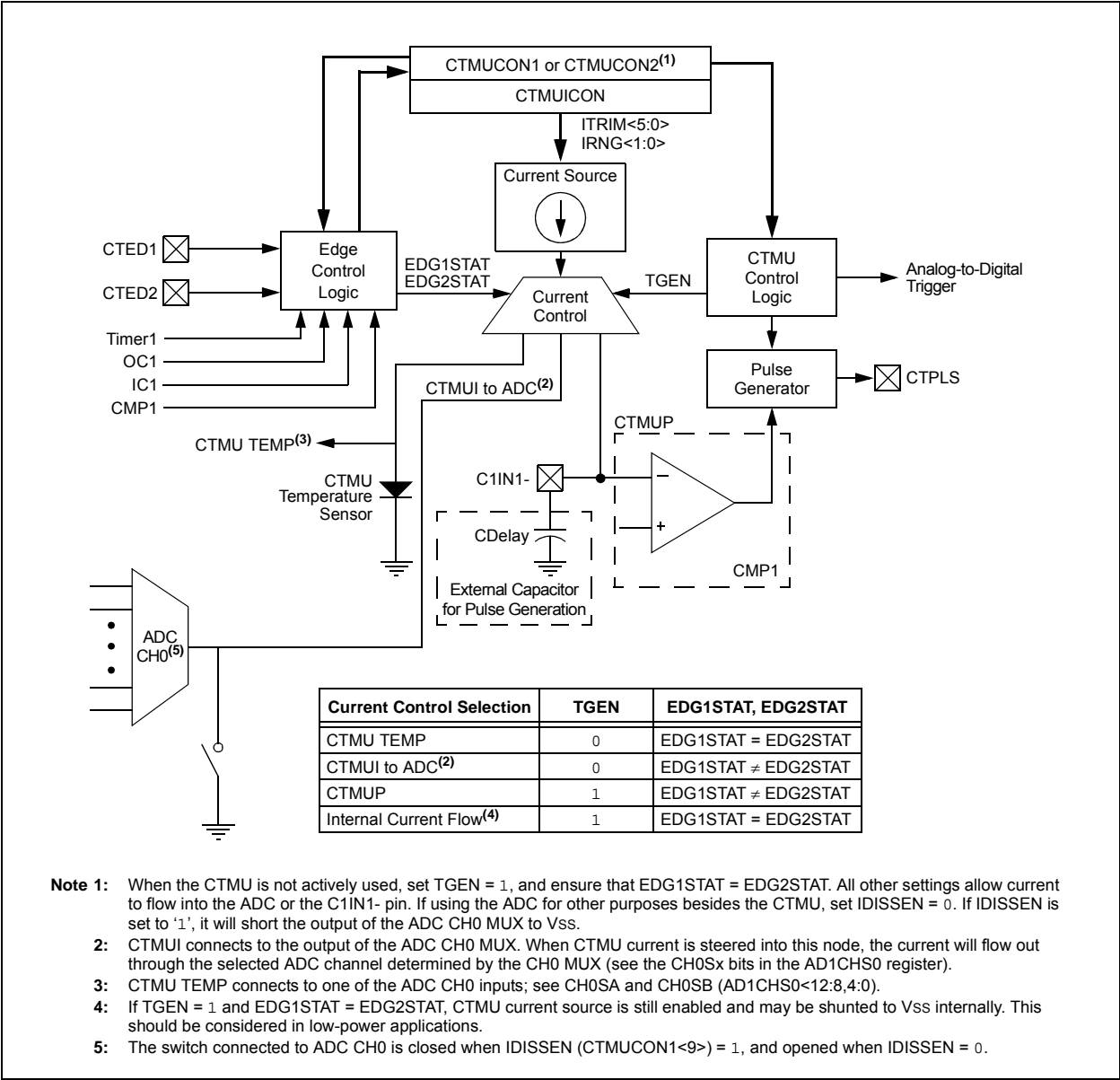
bit 15-12 **F3BP<3:0>**: RX Buffer Mask for Filter 3 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
.
.
.
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F2BP<3:0>**: RX Buffer Mask for Filter 2 bits (same values as bits<15:12>)

bit 7-4 **F1BP<3:0>**: RX Buffer Mask for Filter 1 bits (same values as bits<15:12>)

bit 3-0 **F0BP<3:0>**: RX Buffer Mask for Filter 0 bits (same values as bits<15:12>)

FIGURE 22-1: CTMU BLOCK DIAGRAM



22.1 CTMU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

22.1.1 KEY RESOURCES

- “Charge Time Measurement Unit (CTMU)” (DS70661) in the “dsPIC33/PIC24 Family Reference Manual”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related “dsPIC33/PIC24 Family Reference Manual” Sections
- Development Tools

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings⁽¹⁾

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS ⁽³⁾	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V ⁽³⁾	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V ⁽³⁾	-0.3V to +3.6V
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin ⁽²⁾	300 mA
Maximum current sunk/sourced by any 4x I/O pin	15 mA
Maximum current sunk/sourced by any 8x I/O pin	25 mA
Maximum current sunk by all ports ^(2,4)	200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the “Pin Diagrams” section for the 5V tolerant pins.

4: Exceptions are: dsPIC33EPXXXGP502, dsPIC33EPXXXMC202/502 and PIC24EPXXXGP/MC202 devices, which have a maximum sink/source capability of 130 mA.

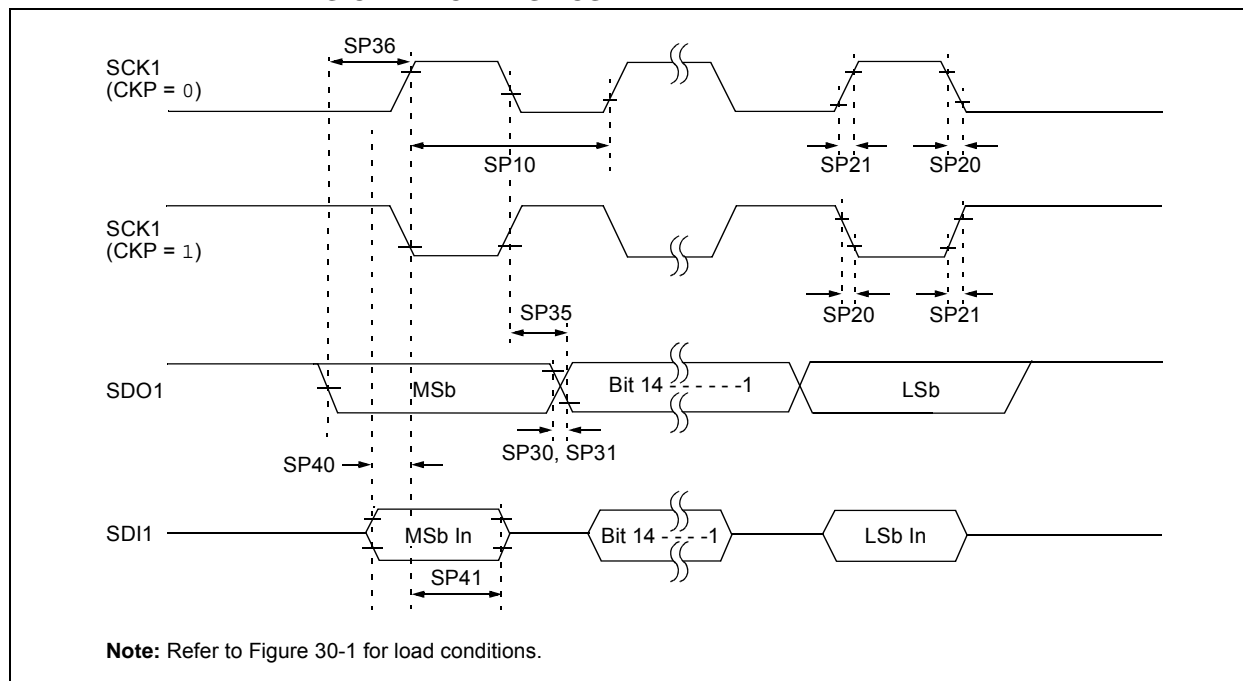
TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended	
Parameter No.	Typ.	Max.	Units	Conditions
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	200	μA	+85°C
DC60c	250	500	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X				
DC60d	25	100	μA	-40°C
DC60a	30	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	350	800	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	550	1000	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X				
DC60d	35	100	μA	-40°C
DC60a	40	100	μA	+25°C
DC60b	250	450	μA	+85°C
DC60c	1000	1200	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X				
DC60d	40	100	μA	-40°C
DC60a	45	100	μA	+25°C
DC60b	350	800	μA	+85°C
DC60c	1100	1500	μA	+125°C

Note 1: IPD (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- MCLR = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

**FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1)
TIMING CHARACTERISTICS**



**TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	(Note 3)
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2sch, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

Note 2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

Note 3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

Note 4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-59: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
ADC Accuracy (10-Bit Mode)							
AD20b	Nr	Resolution	10 Data Bits			bits	
AD21b	INL	Integral Nonlinearity	-0.625	—	0.625	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-1.5	—	1.5	LSb	+85°C < TA ≤ +125°C (Note 2)
AD22b	DNL	Differential Nonlinearity	-0.25	—	0.25	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-0.25	—	0.25	LSb	+85°C < TA ≤ +125°C (Note 2)
AD23b	GERR	Gain Error	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-2.5	—	2.5	LSb	+85°C < TA ≤ +125°C (Note 2)
AD24b	EOFF	Offset Error	-1.25	—	1.25	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-1.25	—	1.25	LSb	+85°C < TA ≤ +125°C (Note 2)
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (10-Bit Mode)							
AD30b	THD	Total Harmonic Distortion ⁽³⁾	—	64	—	dB	
AD31b	SINAD	Signal to Noise and Distortion ⁽³⁾	—	57	—	dB	
AD32b	SFDR	Spurious Free Dynamic Range ⁽³⁾	—	72	—	dB	
AD33b	FNYQ	Input Signal Bandwidth ⁽³⁾	—	550	—	kHz	
AD34b	ENOB	Effective Number of Bits ⁽³⁾	—	9.4	—	bits	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 “Electrical Characteristics”	<p>Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings⁽¹⁾.</p> <p>Removed Parameter DC18 (V_{CORE}) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4).</p> <p>Updated Note 1 in the DC Characteristics: Operating Current (I_{DD}) (see Table 30-6).</p> <p>Updated Note 1 in the DC Characteristics: Idle Current (I_{IDLE}) (see Table 30-7).</p> <p>Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (I_{PD}) (see Table 30-8).</p> <p>Updated Note 1 in the DC Characteristics: Doze Current (I_{DOZE}) (see Table 30-9).</p> <p>Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12).</p> <p>Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14).</p> <p>Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15).</p> <p>Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16).</p> <p>Updated Internal FRC Accuracy Parameter F20a (see Table 30-21).</p> <p>Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).</p>
Section 31.0 “Packaging Information”	Updated packages by replacing references of VLAP with TLA.
“Product Identification System”	Changed VLAP to TLA.